

半導体パッケージ向け製品!

Products for semi-conductor package

微細粉水溶性ソルダペースト Fine powder water soluble solder paste

NP303-WS6104-T6

洗浄性 Washability

従来品 Conventional product **WS6104**

洗浄条件
Cleaning conditions
DI water
40°C 150psi 2min

洗浄性良好
Excellent washability

連続印刷 continuous printing

従来品 Conventional product **WS6104**

**連続印刷による粘度・チクソ低下を抑制
印刷形状維持**
Keep initial viscosity, thixotropy and shape of printing
after continuous printing for 8 hours

ボイド Void

QFN **BGA**

従来品 Conventional product **WS6104** **従来品** Conventional product **WS6104**

ボイド: 23.1% Void ボイド: 5.2% Void **ボイド低減** Less Void

微細開口における印刷性及び溶融性 Printability and Solderability at fine opening

印刷後 After printing **加熱後** After heating

開口径: □75μm
Dimension of opening

印刷性、溶融性良好
Excellent printability and solderability

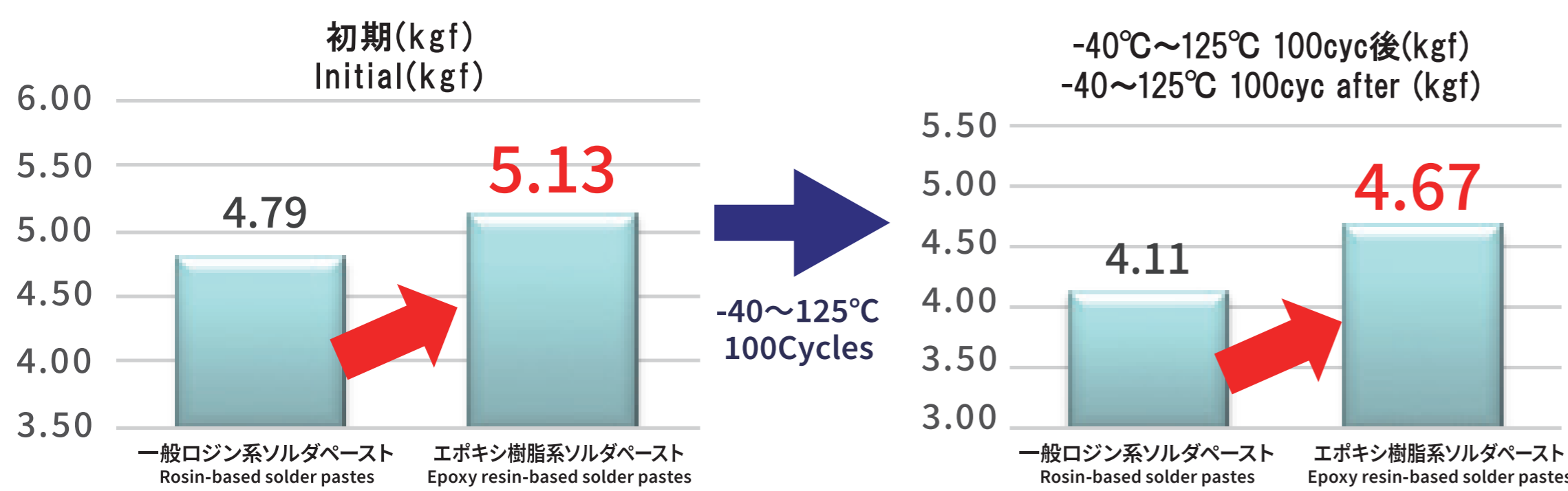
エポキシ樹脂系ソルダペースト Epoxy resin-based solder paste

NP303-EPP101-T6

エポキシ樹脂硬化によりはんだ接合部を補強
Reinforces solder joints by curing epoxy resin

シヤ強度 shear strength

リフロー後のシヤ強度測定結果(0603チップ部品) Shear strength after reflow (0603 chip component)



従来のロジン系ソルダペーストにくらべ、シヤ強度が高く、冷熱衝撃試験後の劣化が少ない
Higher shear strength and less deterioration after thermal shock testing compared to conventional rosin-based solder pastes

ぬれ拡がり比較 Comparison of wettability

	従来品 Conventional product	NP303-EPP101-T6
大気リフロー Air reflow	ふちにはじきが発生 No wetting at edge	ぬれ拡がり良好 Good wetting
N2リフロー 酸素濃度1000ppm N2 Reflow O2 concentration :1000ppm	ふちにはじきが発生 No wetting at edge	ぬれ拡がり良好 Good wetting

ボイド Void

QFN部品実装結果 QFN component mounting

従来品 Conventional epoxy solder paste **NP303-EPP101-T6**

ボイド率: 33.94% Void ratio: 33.94% ボイド率: 12.88% Void ratio: 12.88% ボイド率: 12.3% Void ratio: 12.3%

フラックス成分の流動性が良い為、フラックス成分が接合部に残らず、ボイドを抑制

The excellent fluidity does not make flux remain at joined part and suppresses void.

